MURS320T3G, SURS8320T3G, MURS340T3G, SURS8340T3G, SURS340T3G, MURS360T3G, SURS8360T3G, SURS360T3G



This series employs the state-of-the-art epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes, in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (0.71 to 1.05 Volts Max @ 3.0 A, T_J = 150°C)
- AEC-Q101 Qualified and PPAP Capable
- SURS8 and SURS Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- Pb-Free Packages*

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 217 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 16 mm Tape and Reel, 2500 units per reel
- Polarity: Notch in Plastic Body Indicates Cathode Lead
- Device Meets MSL1 Requirements
- ESD Ratings:
 - ♦ Machine Model, C (> 400 V)
 - ♦ Human Body Model, 3B (> 8 kV)



ON Semiconductor®

http://onsemi.com

ULTRAFAST RECTIFIERS 3.0 AMPERES 200-600 VOLTS



SMC CASE 403 PLASTIC

MARKING DIAGRAM



U3 = Specific Device Code

= D (320T3)

= G (340T3) = J (360T3)

A = Assembly Location

′ = Year

WW = Work Week

ORDERING INFORMATION

		i
Device	Package	Shipping [†]
MURS320T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8320T3G	SMC (Pb-Free)	2,500 / Tape & Reel
MURS340T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8340T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS340T3G	SMC (Pb-Free)	2,500 / Tape & Reel
MURS360T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS8360T3G	SMC (Pb-Free)	2,500 / Tape & Reel
SURS360T3G	SMC (Pb-Free)	2,500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MURS320T3G, SURS8320T3G, MURS340T3G, SURS8340T3G, SURS360T3G, SURS360T3G, SURS360T3G

MAXIMUM RATINGS

Rating	Symbol	MURS320T3G/ SURS8320T3G	MURS340T3G/ SURS8340T3G/ SURS340T3G	MURS360T3G/ SURS8360T3G/ SURS360T3G	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	400	600	V
Average Rectified Forward Current	I _{F(AV)}	3.0 @ T _L = 140°C 4.0 @ T _L = 130°C	3.0 @ T _L = 130°C 4.0 @ T _L = 115°C	3.0 @ T _L = 130°C 4.0 @ T _L = 115°C	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I _{FSM}	75			Α
Operating Junction Temperature	TJ	- 65 to +175			

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Lead	$R_{ hetaJL}$	11	°C/W	Ī
--------------------------------------	---------------	----	------	---

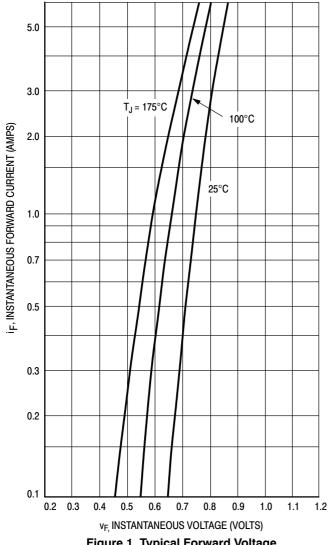
ELECTRICAL CHARACTERISTICS

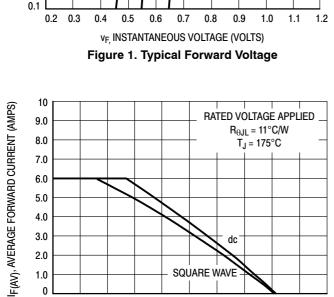
Maximum Instantaneous Forward Voltage (Note 1) $ \begin{aligned} &(i_F=3.0\text{ A},T_J=25^{\circ}\text{C})\\ &(i_F=4.0\text{ A},T_J=25^{\circ}\text{C})\\ &(i_F=3.0\text{ A},T_J=150^{\circ}\text{C}) \end{aligned} $	v _F	0.875 0.89 0.71	1.25 1.28 1.05	1.25 1.28 1.05	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T _J = 25°C) (Rated dc Voltage, T _J = 150°C)	İR	5.0 150	10 250	10 250	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} &(i_F=1.0 \text{ A, di/dt}=50 \text{ A/}\mu\text{s}) \\ &(i_F=0.5 \text{ A, }i_R=1.0 \text{ A, }I_{REC} \text{ to }0.25 \text{ A}) \end{aligned} $	t _{rr}	35 25	75 50	75 50	ns
Maximum Forward Recovery Time (i _F = 1.0 A, di/dt = 100 A/μs, Recovery to 1.0 V)	t _{fr}	25	50	50	ns

^{1.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

MURS320T3G, SURS8320T3G, MURS340T3G, SURS8340T3G, SURS360T3G, SURS360T3G

MURS320T3G/SURS8320T3G





T_C, CASE TEMPERATURE (°C)
Figure 4. Current Derating, Case

140

150

160

170

180 190

130

90 100 110

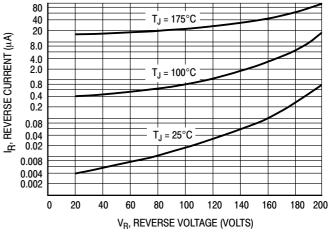


Figure 2. Typical Reverse Current*

* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if V_R is sufficiently below rated V_R .

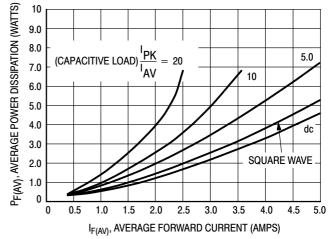


Figure 3. Power Dissipation

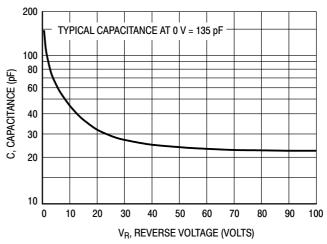
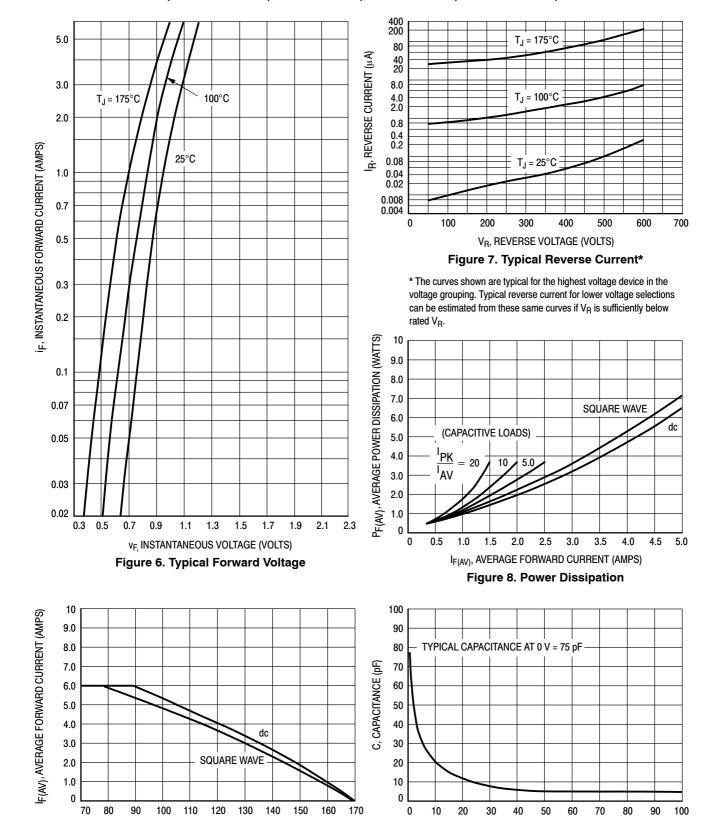


Figure 5. Typical Capacitance

MURS320T3G, SURS8320T3G, MURS340T3G, SURS8340T3G, SURS340T3G, MURS360T3G, SURS8360T3G, SURS360T3G

MURS340T3G, SURS8340T3G, SURS340T3G, MURS360T3G, SURS8360T3G, SURS360T3G



T_C, CASE TEMPERATURE (°C) Figure 9. Current Derating, Case

V_R, REVERSE VOLTAGE (VOLTS) Figure 10. Typical Capacitance

70

100

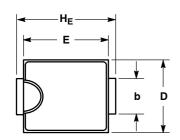
0

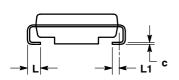
20

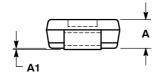
MURS320T3G, SURS8320T3G, MURS340T3G, SURS8340T3G, SURS340T3G, MURS360T3G, SURS8360T3G, SURS360T3G

PACKAGE DIMENSIONS

SMC PLASTIC PACKAGE CASE 403-03 **ISSUE E**





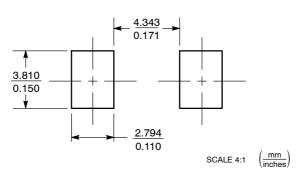


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.
- 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.90	2.13	2.41	0.075	0.084	0.095	
A1	0.05	0.10	0.15	0.002	0.004	0.006	
b	2.92	3.00	3.07	0.115	0.118	0.121	
С	0.15	0.23	0.30	0.006	0.009	0.012	
D	5.59	5.84	6.10	0.220	0.230	0.240	
E	6.60	6.86	7.11	0.260	0.270	0.280	
HE	7.75	7.94	8.13	0.305	0.313	0.320	
L	0.76	1.02	1.27	0.030	0.040	0.050	
L1	0.51 REF				0.020 REF	-	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and war engineer trademarks of semiconductor components industries, Ite (SciLLC) solitate services are injective to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative